

P-Channel 1.8-V (G-S) MOSFET

FEATURES

- TrenchFET® Power MOSFET: 1.8-V Rated
- Gate-Source ESD Protected: 2000 V
- High-Side Switching
- Low On-Resistance: 1.2 Ω
- Low Threshold: 0.8 V (typ)
- Fast Switching Speed: 14 ns
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

BENEFITS

- Ease in Driving Switches
- Low Offset (Error) Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Low Battery Voltage Operation

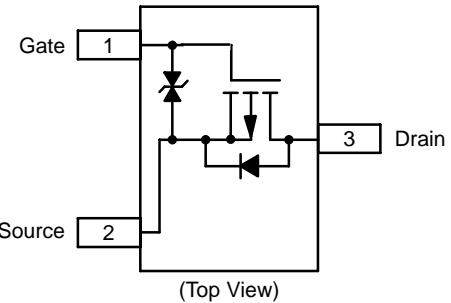
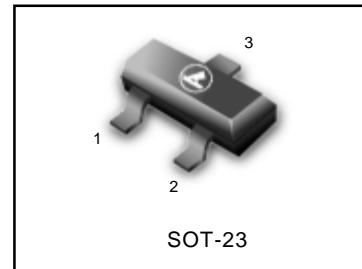
APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers

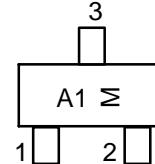
ORDERING INFORMATION

Device	Marking	Shipping
LSI1013LT1G S-LSI1013LT1G	A1	3000/Tape&Reel
LSI1013LT3G S-LSI1013LT3G	A1	10000/Tape&Reel

LSI1013LT1G
S-LSI1013LT1G



MARKING DIAGRAM



A1 = Specific Device Code
M = Month Code

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	5 secs	Steady State	Unit	
Drain-Source Voltage	V_{DS}	-20	± 6	V	
Gate-Source Voltage	V_{GS}				
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^b	I_D	-400	-350	mA	
		-300	-275		
Pulsed Drain Current ^a	I_{DM}	-1000			
Continuous Source Current (diode conduction) ^b	I_S	-275	-250		
Maximum Power Dissipation	P_D	225		mW	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150		°C	
Gate-Source ESD Rating (HBM, Method 3015)	ESD	2000		V	

Notes

- d. Pulse width limited by maximum junction temperature.
e. Surface Mounted on FR4 Board.

LSI1013LT1G , S-LSI1013LT1G
SPECIFICATIONS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

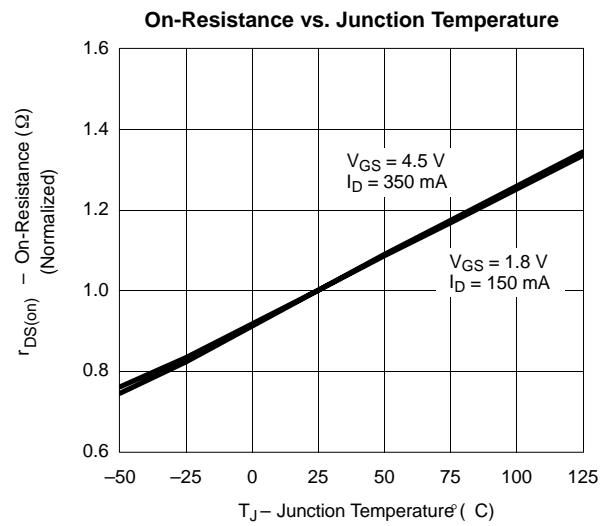
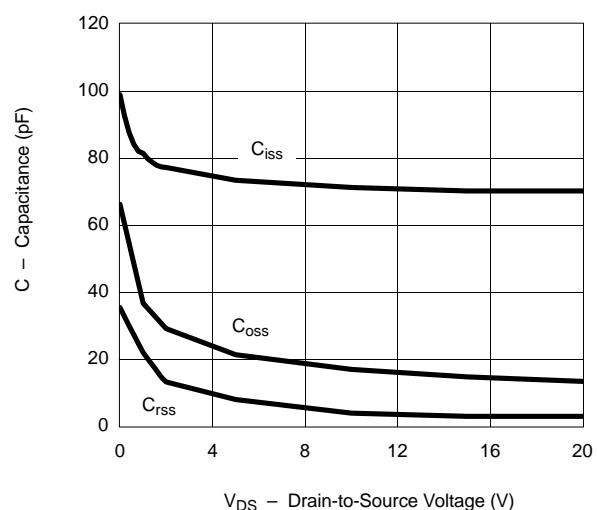
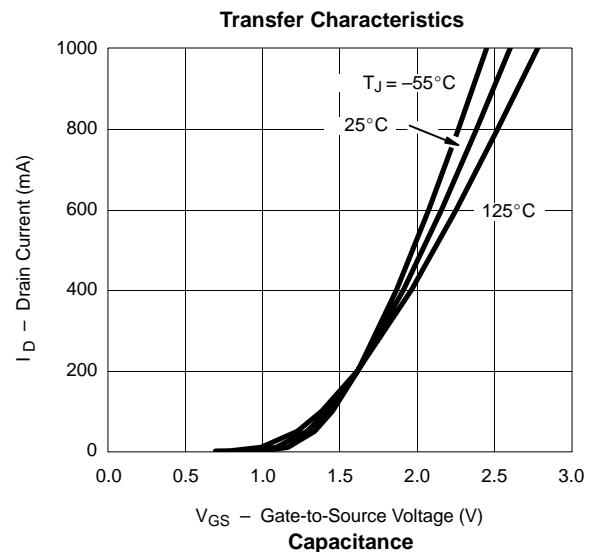
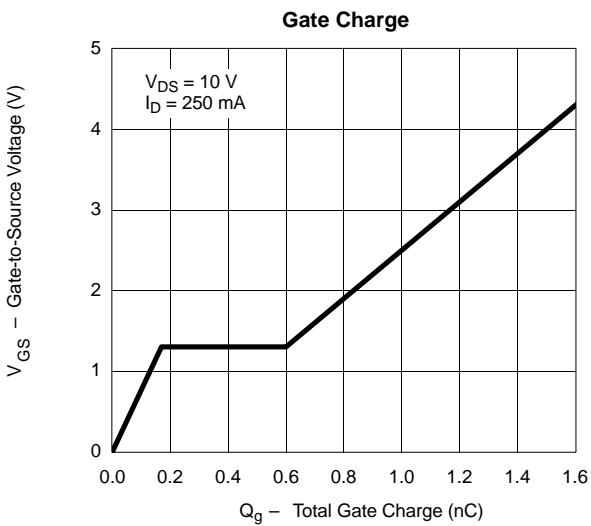
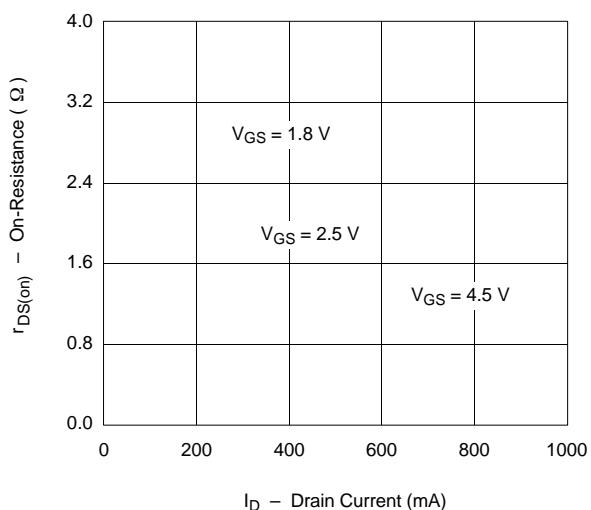
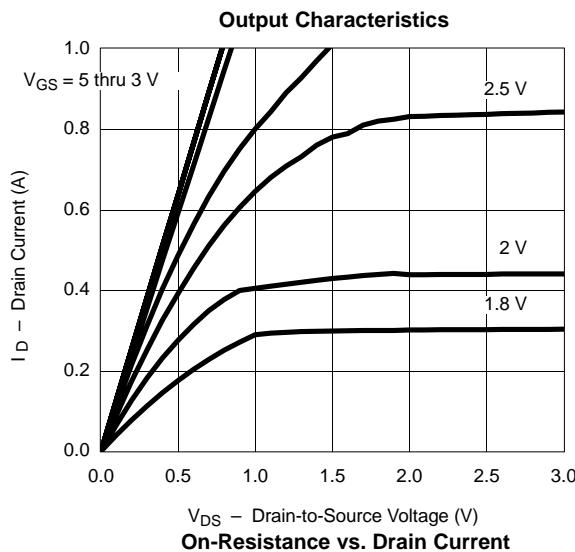
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-0.45			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$		± 1	± 2	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$		-0.3	-100	nA
		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$			-5	μA
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-700			mA
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = -4.5 \text{ V}, I_D = -350 \text{ mA}$		0.8	1.2	Ω
		$V_{GS} = -2.5 \text{ V}, I_D = -300 \text{ mA}$		1.2	1.6	
		$V_{GS} = -1.8 \text{ V}, I_D = -10 \text{ mA}$		1.8	2.7	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10 \text{ V}, I_D = -250 \text{ mA}$		0.4		s
Diode Forward Voltage ^a	V_{SD}	$I_S = -150 \text{ mA}, V_{GS} = 0 \text{ V}$		-0.8	-1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -250 \text{ mA}$		1500		pC
Gate-Source Charge	Q_{gs}			150		
Gate-Drain Charge	Q_{gd}			450		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -10 \text{ V}, R_L = 47 \Omega$ $I_D \approx -200 \text{ mA}, V_{GEN} = -4.5 \text{ V}, R_G = 10 \Omega$		5		ns
Rise Time	t_r			9		
Turn-Off Delay Time	$t_{d(\text{off})}$			35		
Fall Time	t_f			11		

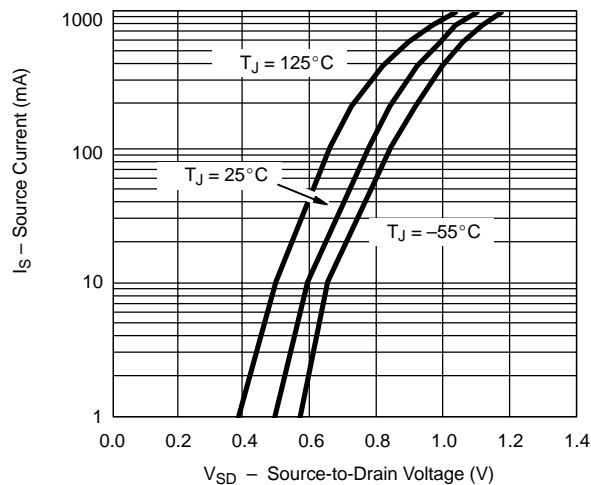
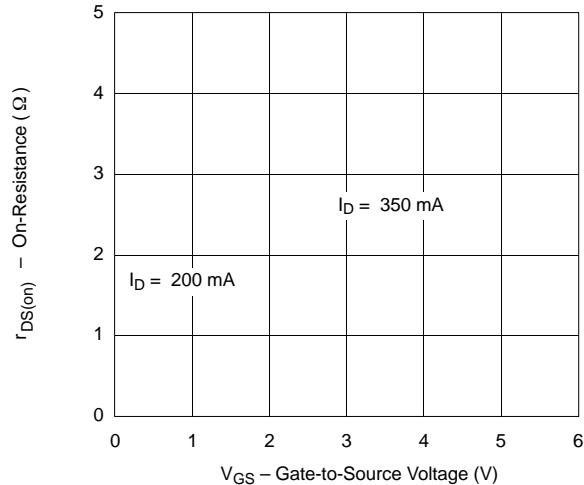
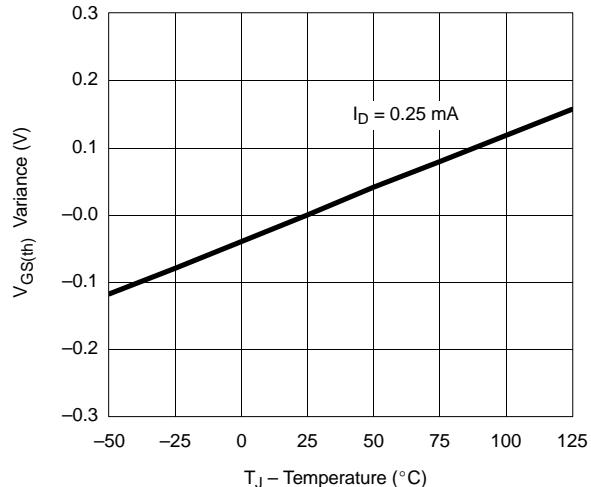
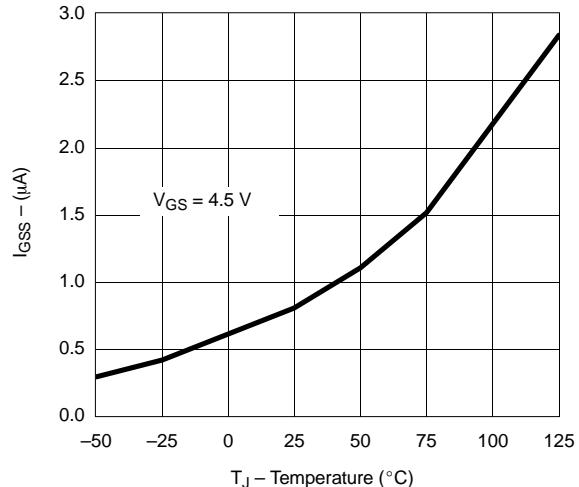
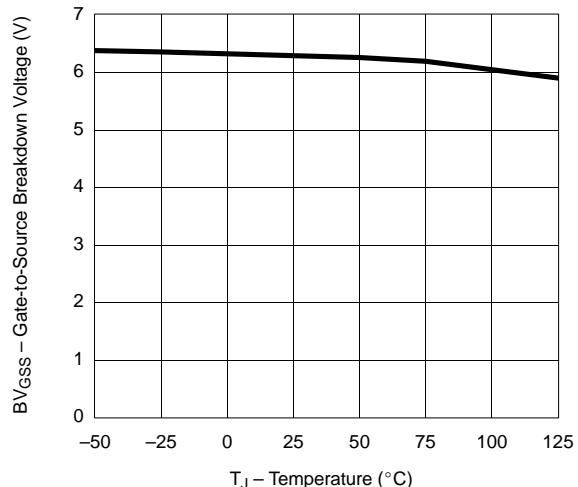
Notes

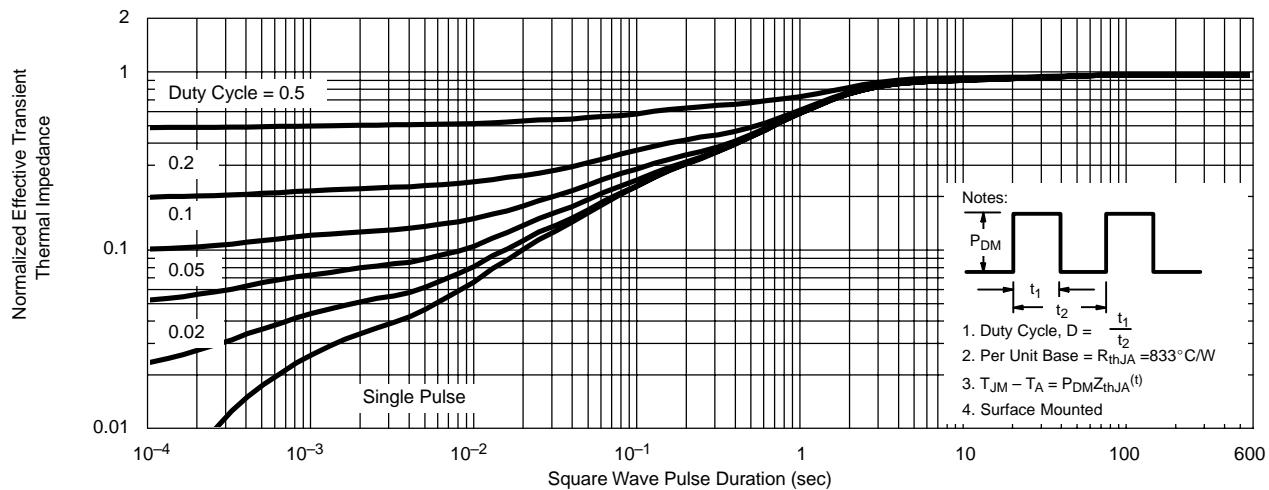
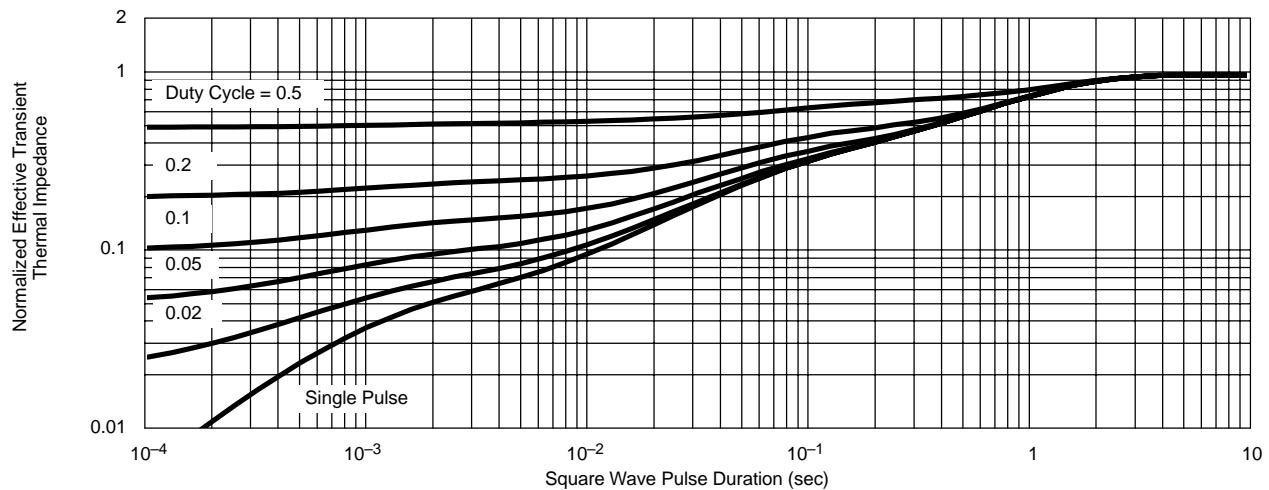
- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

LSI1013LT1G , S-LSI1013LT1G
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS NOTED)

For the following graphs, p-channel negative polarities for all voltage and current values are represented as positive values.

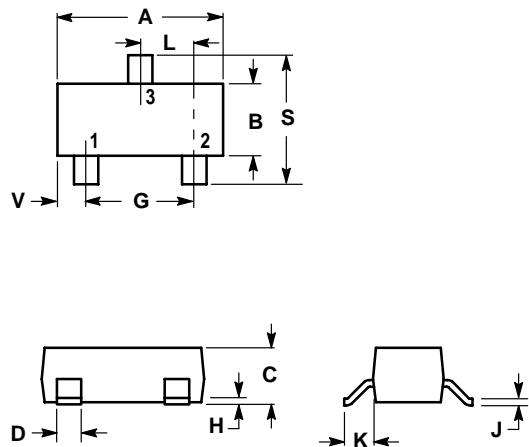


LSI1013LT1G , S-LSI1013LT1G
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS NOTED)
Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

Threshold Voltage Variance vs. Temperature

 I_{GSS} vs. Temperature

 BV_{GSS} vs. Temperature


LSI1013LT1G , S-LSI1013LT1G
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS NOTED)
Normalized Thermal Transient Impedance, Junction-to-Ambient (SC-75A)

Normalized Thermal Transient Impedance, Junction-to-Foot


LSI1013LT1G , S-LSI1013LT1G
SOT-23
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M,1982
2. CONTROLLING DIMENSION: INCH.



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.1102	0.1197	2.80	3.04
B	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
H	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
V	0.0177	0.0236	0.45	0.60

